

Pricing Supplement

Date: 6 February 2026

CIMB BANK BERHAD (REGISTRATION NO. 197201001799 (13491-P))("Issuer")

Issuance of CIMB Bank Berhad 2026 Renminbi Bonds (Series 1) (Bond Connect) ("Bonds") pursuant to Renminbi ("RMB") 10.0 billion bond programme where the Issuer may issue RMB bonds in multiple series in an aggregate principal amount of up to RMB 10.0 billion on the China Inter-bank Bond Market

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| 1. | Issuer | : | CIMB Bank Berhad |
| 2. | Issue Date | : | 9 February 2026 |
| 3. | Issue Amount | : | RMB3,000,000,000.00 |
| 4. | Tenor | : | 2 years |
| 5. | Coupon Rate | : | 1.98% |
| 6. | Details on Utilisation of Proceeds | : | For the net proceeds from the offering of the Bonds: (i) not less than RMB200 million of the net proceeds will be retained onshore to support the operations and development of the Issuer's Shanghai Branch; and (ii) the remaining net proceeds may be remitted offshore to fund the Issuer's and its subsidiaries' offshore RMB assets and/or converted to other currencies (such as Malaysian Ringgit, U.S. dollars) to support the operations of the Issuer and its subsidiaries offshore, including but not limited to providing financing to (i) the People's Republic of China ("PRC")-backed or PRC-linked corporates/enterprises, (ii) PRC banks, (iii) corporates/enterprises that have trade relationships with Chinese enterprises and (iv) the implementation of major projects between PRC and Malaysia. |
| 7. | Rating | : | AAA by China Chengxin International Credit Rating Co., Ltd.. |
| 8. | Other Conditions | : | Please refer to the Offering Circular dated 28 January 2026 in relation to the Bonds. |